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May 2013

# TIL111M, TIL117M, MOC8100M General Purpose 6-Pin Phototransistor Optocouplers

#### **Features**

- UL Recognized (File # E90700)
- VDE Recognized (File #102497 for white package)Add Option V (e.g., TIL111VM)

#### **Applications**

- Power Supply Regulators
- Digital Logic Inputs
- Microprocessor Inputs
- Appliance Sensor Systems
- Industrial Controls

#### **General Description**

The MOC8100M, TIL111M, and TIL117M optocouplers consist of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 6-pin dual in-line package.

#### **Schematic**

# ANODE 1 0 6 BASE CATHODE 2 0 5 COLLECTOR NC 3 0 4 EMITTER

Figure 1. Schematic

#### **Package Outlines**

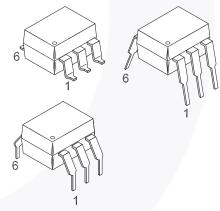


Figure 2. Package Outlines

## **Safety and Insulation Ratings**

As per IEC60747-5-2. This optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Symbol            | Parameter  | Min.            | Тур.      | Max. | Unit              |
|-------------------|--|-----------------|-----------|------|-------------------|
|                   | Installation Classifications per DIN VDE 0110/1.89 Table 1   |                 |           |      |                   |
|                   | For Rated Mains Voltage < 150 V <sub>RMS</sub>   |                 | I–IV      |      |                   |
|                   | For Rated Mains Voltage < 300 V <sub>RMS</sub>   |                 | I–IV      |      |                   |
|                   | Climatic Classification  |                 | 55/100/21 |      |                   |
|                   | Pollution Degree (DIN VDE 0110/1.89)   |                 | 2         |      |                   |
| CTI               | Comparative Tracking Index   | 175             |           |      |                   |
| V <sub>PR</sub>   | Input to Output Test Voltage, Method b, $V_{IORM} \times 1.875 = V_{PR}$ , 100% Production Test with $t_m = 1$ s, Partial Discharge < 5 pC | 1594            |           |      |                   |
|                   | Input to Output Test Voltage, Method a, $V_{IORM} \times 1.5 = V_{PR}$ , Type and Sample Test with $t_m = 60$ s, Partial Discharge < 5 pC  | 1275            |           |      |                   |
| V <sub>IORM</sub> | Maximum Working Insulation Voltage   | 850             |           |      | V <sub>peak</sub> |
| V <sub>IOTM</sub> | Highest Allowable Over Voltage   | 6000            |           |      | V <sub>peak</sub> |
|                   | External Creepage  | 7               |           |      | mm                |
|                   | External Clearance   | 7               |           |      | mm                |
|                   | Insulation Thickness   | 0.5             |           |      | mm                |
| R <sub>IO</sub>   | Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V  | 10 <sup>9</sup> |           |      | Ω                 |

#### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol              | Parameter  |    | Device          | Value          | Units |
|---------------------|--|----|-----------------|----------------|-------|
| Total Devi          | ce   |    |                 |                | l     |
| T <sub>STG</sub>    | Storage Temperature                                    |    | All             | -40 to +150    | °C    |
| T <sub>OPR</sub>    | Operating Temperature                                  |    | All             | -40 to +100    | °C    |
| T <sub>SOL</sub>    | Lead Solder Temperature                                |    | All             | 260 for 10 sec | °C    |
| P <sub>D</sub>      | Total Device Power Dissipation @ T <sub>A</sub> = 25°C |    | All             | 250            | mW    |
|                     | Derate Above 25°C                                      |    |                 | 2.94           | mW/°C |
| Emitter             |  |    |                 |                |       |
| I <sub>F</sub>      | DC/Average Forward Input Current                       |    | All             | 60             | mA    |
| V <sub>R</sub>      | Reverse Input Voltage                                  |    | TIL111M         | 3              | V     |
|                     |  | МО | C8100M, TIL117M | 6              |       |
| I <sub>F</sub> (pk) | Forward Current – Peak (300 µs, 2% Duty Cycle)         |    | All             | 3              | Α     |
| $P_{D}$             | LED Power Dissipation @ T <sub>A</sub> = 25°C          |    | All             | 120            | mW    |
|                     | Derate Above 25°C                                      |    |                 | 1.41           | mW/°C |
| Detector            | 7  |    |                 |                |       |
| $V_{CEO}$           | Collector-Emitter Voltage                              |    | All             | 30             | V     |
| V <sub>CBO</sub>    | Collector-Base Voltage                                 |    | All             | 70             | V     |
| V <sub>ECO</sub>    | Emitter-Collector Voltage                              | TI | L111M, TIL117M  | 7              | V     |
| $V_{EBO}$           | Emitter-Base Voltage                                   |    | All             | 7              |       |
| $P_{D}$             | Detector Power Dissipation @ T <sub>A</sub> = 25°C     |    | All             | 150            | mW    |
|                     | Derate Above 25°C                                      |    |                 | 1.76           | mW/°C |

#### **Electrical Characteristics**

 $T_A = 25$ °C unless otherwise specified.

#### **Individual Component Characteristics**

| Symbol            | Parameter                              | Test Conditions  |                            | Device               | Min. | Тур.* | Max. | Unit |
|-------------------|--|--|----------------------------|----------------------|------|-------|------|------|
| Emitter           |  |  |                            |                      |      | •     | '    |      |
| V <sub>F</sub>    |  |  | TIL111M                    |                      | 1.2  | 1.4   | V    |      |
|                   | Voltage                                | $I_F = 10 \text{ mA for}$ $T_A = 0^{\circ}\text{C to } 70^{\circ}\text{C}$ |                            | MOC8100M,            |      | 1.2   | 1.4  |      |
|                   |  | MOC8100M,  | T <sub>A</sub> = -55°C     | TIL117M              |      | 1.32  |      |      |
|                   |  | I <sub>F</sub> = 16 mA for<br>TIL117M                                      | T <sub>A</sub> = +100°C    |                      |      | 1.10  |      |      |
| I <sub>R</sub>    | Reverse Leakage                        | V <sub>R</sub> = 3.0 V   |                            | TIL111M, TIL117M     |      | 0.001 | 10   | μΑ   |
|                   | Current                                | V <sub>R</sub> = 6.0 V   |                            | MOC8100M             |      | 0.001 | 10   | μΑ   |
| Detector          |  |  |                            |                      |      |       |      |      |
| BV <sub>CEO</sub> | Collector-Emitter<br>Breakdown Voltage | I <sub>C</sub> = 1.0 mA, I <sub>F</sub> :                                  | = 0                        | All                  | 30   | 100   |      | V    |
| BV <sub>CBO</sub> | Collector-Base<br>Breakdown Voltage    | $I_C = 10 \mu A, I_F = 0$  |                            | All                  | 70   | 120   |      | V    |
| BV <sub>EBO</sub> | Emitter-Base<br>Breakdown Voltage      | I <sub>E</sub> = 10 μA, I <sub>F</sub> = 0                                 |                            | All                  | 7    | 10    |      | V    |
| BV <sub>ECO</sub> | Emitter-Collector<br>Breakdown Voltage | I <sub>F</sub> = 100 μA, I <sub>F</sub> = 0                                |                            | TIL111M, TIL117M     | 7    | 10    |      | V    |
| I <sub>CEO</sub>  | Collector-Emitter                      | V <sub>CE</sub> = 10 V, I <sub>F</sub> =                                   | : 0                        | TIL111M, TIL117M     |      | 1     | 50   | nA   |
| Dark Current      | Dark Current                           | V <sub>CE</sub> = 5 V, T <sub>A</sub> =                                    | 25°C                       | MOC8100M             |      | 0.5   | 25   | nA   |
|                   |  | V <sub>CE</sub> = 30 V, I <sub>F</sub> =                                   | : 0, T <sub>A</sub> = 70°C | TIL117M,<br>MOC8100M |      | 0.2   | 50   | μΑ   |
| I <sub>CBO</sub>  | Collector-Base Dark                    | V <sub>CB</sub> = 10 V   |                            | TIL111M, TIL117M     |      |       | 20   | nA   |
| I <sub>CBO</sub>  | Current                                | V <sub>CB</sub> = 5 V  |                            | MOC8100M             |      |       | 10   | nA   |
| C <sub>CE</sub>   | Capacitance                            | $V_{CE} = 0 \text{ V, f} = 1$  | MHz                        | All                  |      | 8     |      | pF   |

<sup>\*</sup>All Typical values at  $T_A = 25$ °C

# **Electrical Characteristics** (Continued)

 $T_A = 25$ °C unless otherwise specified.

#### **Transfer Characteristics**

| Symbol             | Parameter  | Test Conditions  | Device      | Min | Тур* | Max | Unit |
|--------------------|--|--|-------------|-----|------|-----|------|
| DC Chara           | cteristics   |  |             |     |      |     |      |
| CTR <sub>CE</sub>  | Current Transfer Ratio,<br>Collector to Emitter        | I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 10 V   | TIL117M     | 50  |      |     | %    |
|                    |  | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V   | MOC8100M 50 |     |      | %   |      |
|                    |  | I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 5 V,<br>T <sub>A</sub> = 0°C to +70°C             |             | 30  |      |     |      |
| I <sub>C(ON)</sub> | On-State Collector Current (Phototransistor Operation) | I <sub>F</sub> = 16 mA, V <sub>CE</sub> = 0.4 V  | TIL111M     | 2   |      |     | mA   |
|                    | On-State Collector Current (Photodiode Operation)      | I <sub>F</sub> = 16 mA, V <sub>CB</sub> = 0.4 V  |             | 7   |      |     | μA   |
| CL (SAI)           | Collector-Emitter Saturation Voltage                   | $I_C = 500 \mu A, I_F = 10 mA$   | TIL117M     |     |      | 0.4 | V    |
|                    |  | I <sub>C</sub> = 2 mA, I <sub>F</sub> = 16 mA  | TIL111M     |     |      | 0.4 |      |
|                    |  | I <sub>C</sub> = 100 μA, I <sub>F</sub> = 1 mA   | MOC8100M    |     |      | 0.5 |      |
| AC Charac          | cteristics   |  |             |     | •    |     |      |
| c <sub>ON</sub>    | Turn-On Time   | $I_C = 2 \text{ mA}, V_{CC} = 10 \text{ V},$   | MOC8100M    |     |      | 20  | μs   |
|                    |  | $R_L = 100 \Omega \text{ (Fig. 13)}$   | TIL117M     |     |      | 10  |      |
| C <sub>OFF</sub>   | Turn-Off Time  |  | MOC8100M    |     |      | 20  | μs   |
|                    |  |  | TIL117M     |     |      | 10  |      |
| t <sub>r</sub>     | Rise Time  |  | MOC8100M    |     | 2    |     | μs   |
| t <sub>f</sub>     | Fall Time  |  | TIL117M     |     | 2    |     |      |
| t <sub>r</sub>     | Rise Time<br>(Phototransistor Operation)               | $I_{C(ON)} = 2 \text{ mA}, V_{CC} = 10 \text{ V},$<br>$R_L = 100 \Omega \text{ (Fig. 13)}$ | TIL111M     |     |      | 10  | μs   |
| t <sub>f</sub>     | Fall Time<br>(Phototransistor Operation)               |  |             |     |      |     |      |

#### **Isolation Characteristics**

| Symbol           | Characteristic                 | Test Conditions                        | Min.             | Тур.* | Max. | Units               |
|------------------|--------------------------------|--|------------------|-------|------|---------------------|
| V <sub>ISO</sub> | Input-Output Isolation Voltage | f = 60 Hz, t = 1 s                     | 7500             |       |      | V <sub>AC(PK)</sub> |
| R <sub>ISO</sub> | Isolation Resistance           | V <sub>I-O</sub> = 500 V <sub>DC</sub> | 10 <sup>11</sup> |       |      | Ω                   |
| C <sub>ISO</sub> | Isolation Capacitance          | $V_{I-O} = 0$ , $f = 1 MHz$            |                  | 0.2   |      | pF                  |

<sup>\*</sup>All Typical values at  $T_A = 25$ °C.

### **Typical Performance Characteristics**

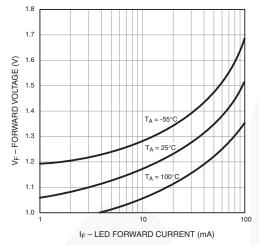


Figure 3. LED Forward Voltage vs. Forward Current

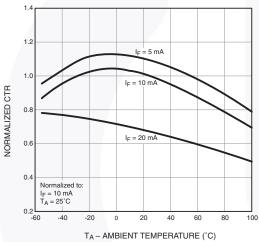


Figure 5. Normalized CTR vs. Ambient Temperature

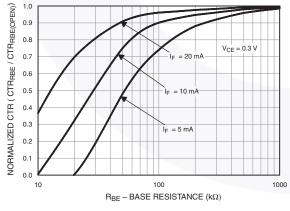


Figure 7. CTR vs. RBE (Saturated)

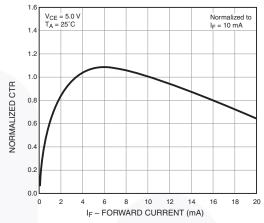


Figure 4. Normalized CTR vs. Forward Current

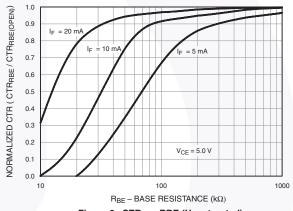


Figure 6. CTR vs. RBE (Unsaturated)

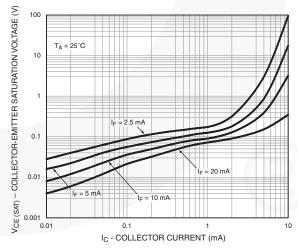


Figure 8. Collector-Emitter Saturation Voltage vs Collector Current

### **Typical Performance Characteristics** (Continued)

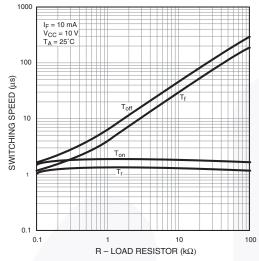


Figure 9. Switching Speed vs. Load Resistor

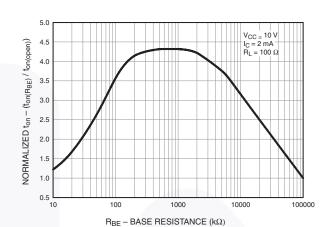


Figure 10. Normalized  $t_{on}$  vs.  $R_{BE}$ 

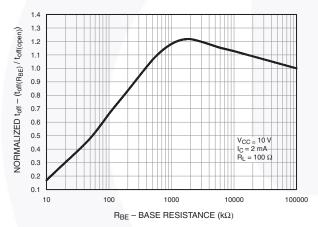
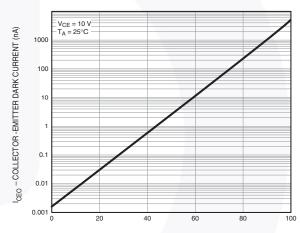


Figure 11. Normalized toff vs. RBE



 $T_A$  – AMBIENTTEMPERATURE (°C)

Figure 12. Dark Current vs. Ambient Temperature

#### TEST CIRCUIT

# V<sub>CC</sub> = 10 V INPUT OUTPUT Adjust IF to produce Ic = 2 mA

#### WAVEFORMS

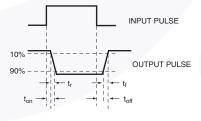


Figure 13. Switching Time Test Circuit and Waveforms



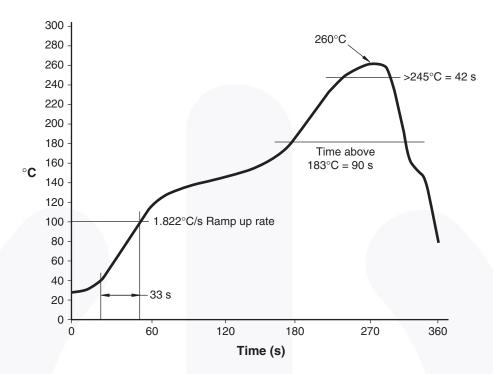
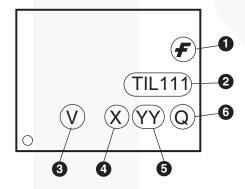


Figure 14. Reflow Profile

# **Ordering Information**

| Option    | Order Entry Identifier (Example) | Description                            |
|-----------|----------------------------------|--|
| No option | TIL111M                          | Standard Through-Hole Device           |
| S         | TIL111SM                         | Surface Mount Lead Bend                |
| SR2       | TIL111SR2M                       | Surface Mount; Tape and Reel           |
| Т         | TIL111TM                         | 0.4" Lead Spacing                      |
| V         | TIL111VM                         | VDE 0884                               |
| TV        | TIL111TVM                        | VDE 0884, 0.4" Lead Spacing            |
| SV        | TIL111SVM                        | VDE 0884, Surface Mount                |
| SR2V      | TIL111SR2VM                      | VDE 0884, Surface Mount, Tape and Reel |

# **Marking Information**



| Definitions |  |  |  |  |  |
|-------------|--|--|--|--|--|
| 1           | Fairchild logo   |  |  |  |  |
| 2           | Device number  |  |  |  |  |
| 3           | VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table) |  |  |  |  |
| 4           | One-digit year code, e.g., '3'   |  |  |  |  |
| 5           | Two-digit work week ranging from '01' to '53'  |  |  |  |  |
| 6           | Assembly package code  |  |  |  |  |

<sup>\*</sup>Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.

# **Carrier Tape Specification**

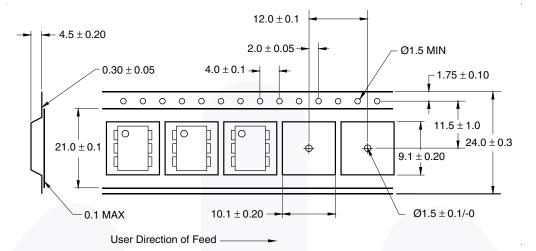
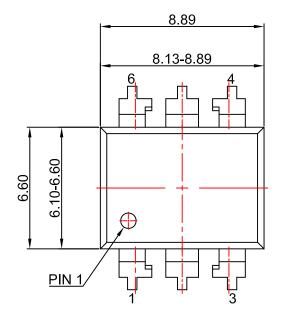
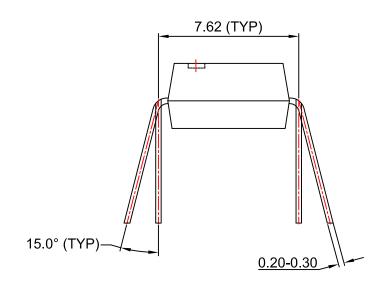
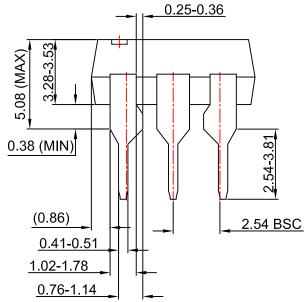


Figure 15. Carrier Tape Specification



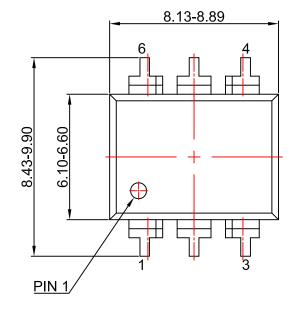


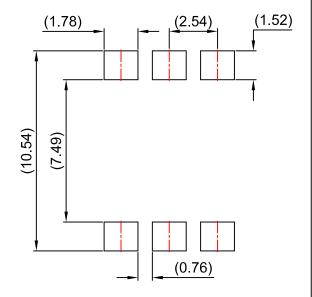


#### NOTES:

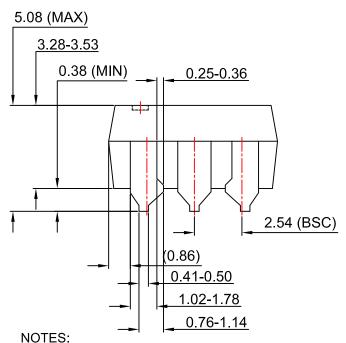
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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVSION: MKT-N06BREV4.

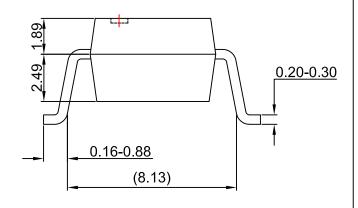






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